

**Amendments to the Specification**

***Please insert the following paragraph on page 1, between the title and the heading "BACKGROUND OF THE INVENTION":***

This is a divisional of U.S. Patent Application Number 10/079,262, filed February 21, 2002, the entire contents of each of which are hereby incorporated herein by reference for all purposes as if fully set forth herein.

***Please replace paragraph [0140] with the following new paragraph:***

[0140] However, if all of the sensors 340 do not contact the bottom surface of the FOUP 130 sufficiently, the FOUP 130 is determined as not having been properly placed on the load port. Accordingly, the semiconductor manufacturing process does not proceed until the FOUP 130 is properly placed on the load port 300. Also, if the FOUP 130 does not contain any wafers even though it is sensed as resting properly on the support member 300 of the load port, a semiconductor manufacturing process does not proceed.